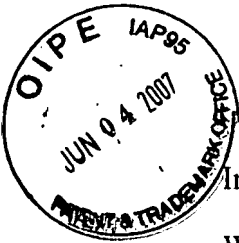


2815 /fw

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
BEFORE THE BOARD OF PATENT APPEALS AND INTERFERENCES



In re application of

WILLIAM P. STEARNS ET AL.

Serial No. 09/678.318 (TI-25833.1)

Filed October 3, 2000

For: OPTIMIZED CIRCUIT DESIGN LAYOUT FOR HIGH
PERFORMANCE BALL GRID ARRAY PACKAGES

Art Unit 2815

Examiner N. Drew Richards

Customer No. 23494

Appeal No. 2007-0698

Mail Stop Amendment
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING OR TRANSMISSION UNDER 37 CFR 1.8

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J-31-07
[Signature]
Jay M. Cantor, Reg. No. 19,906

Sir:

RESPONSE TO REMAND UNDER
37 C.F.R. § 41.50(a)(1) and ORDER UNDER 37 C.F.R. 41.50(d)

In response to the Remand and Order, prior to responding to the specifics of the remand, a brief background will be provided so that the response can be better understood.

In the formation of a semiconductor package, which comprises the semiconductor chip, the substrate and the interconnecting wiring, the wiring and conductive regions on